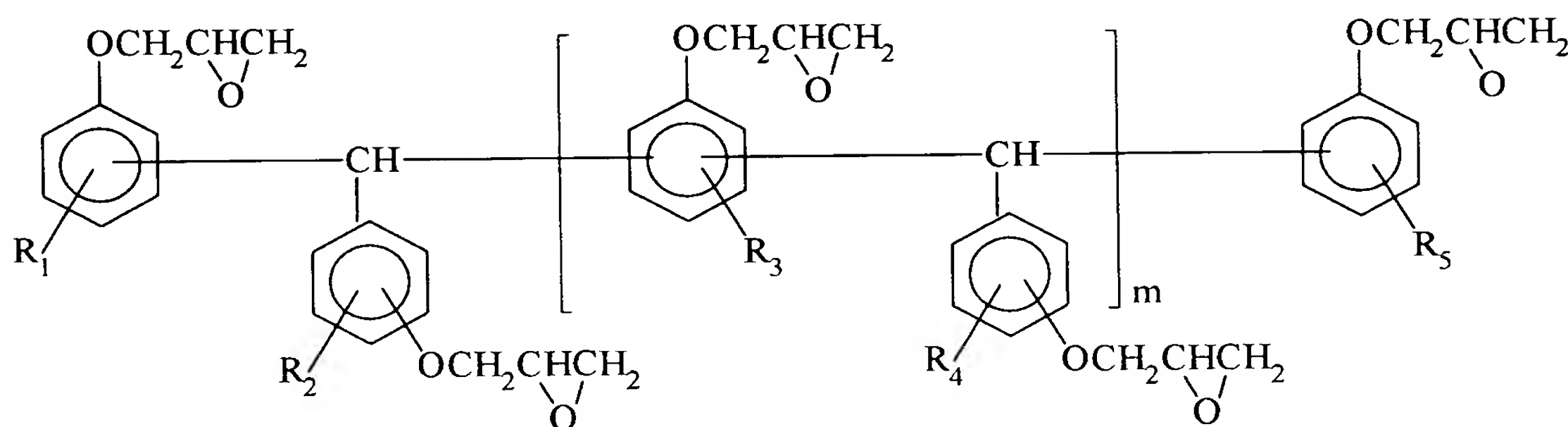


wherein each of R<sub>1</sub> to R<sub>5</sub> is a hydrogen atom and m is 0 or a positive number of 5 or less, wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight, and heating the tablet to be melt-cured, thereby forming the cured product.

3. A process for producing a semiconductor device having substantially no bowing, said semiconductor device comprising an insulating substrate, a semiconductor element mounted on one side of the insulating substrate via a plural connecting electrodes, and a cured resin layer sealing a void between the insulating substrate and the semiconductor element, comprising the steps of:

heat-melting a tablet comprising an epoxy resin composition, said epoxy resin composition comprising a curing agent and an epoxy resin represented by the general formula (1):

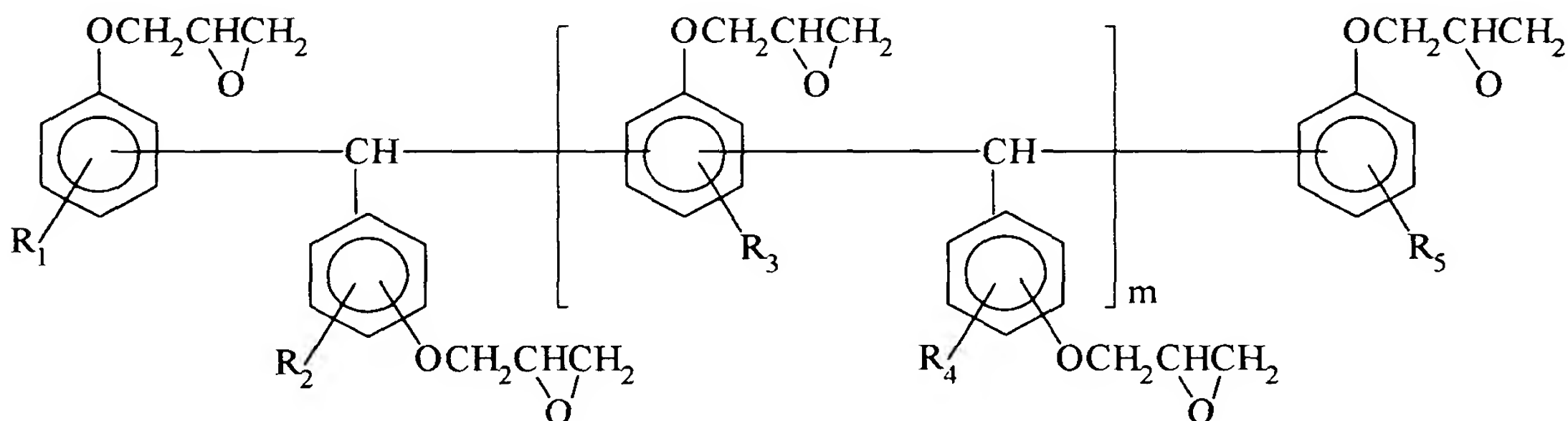


wherein each of R<sub>1</sub> to R<sub>5</sub> is a hydrogen atom and m is 0 or a positive number of 5 or less, wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight, and filling the void and curing the tablet, thereby forming the cured resin layer.

4. The process of any one of claims 1 to 3, wherein said tablet is produced by a process comprising preparing a molten product of said epoxy resin composition in an uncured state and thereafter cooling and solidifying the molten product.

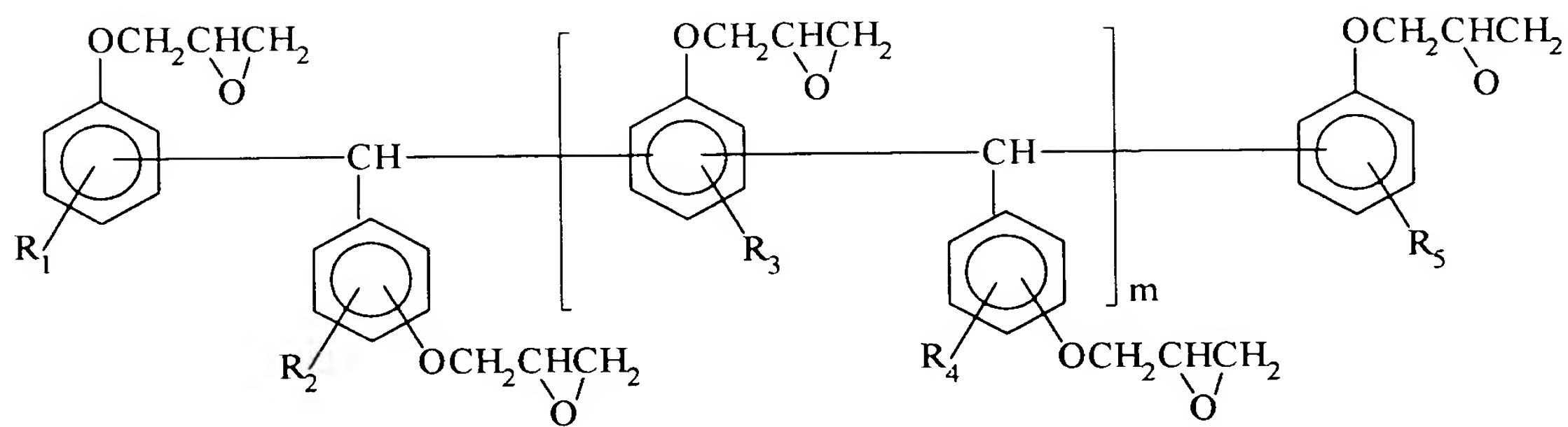
5. The process of any one of claims 1 to 3, wherein a compression ratio of the tablet is 98% or more and/or the glass transition temperature of a cured product of the table is 120°C or more

6. A method for preventing generation of bowing of a wafer, said method comprising forming a cured resin layer on a wafer by using a tablet comprising an epoxy resin composition, said epoxy resin composition comprising an epoxy resin represented by the general formula (1):



wherein each of  $R_1$  to  $R_5$  is a hydrogen atom and  $m$  is 0 or a positive number of 5 or less and a curing agent, wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight.

7. A method for preventing generation of bowing of a semiconductor device, said method comprising sealing semiconductor elements on one side of an insulating substrate by using a tablet comprising an epoxy resin composition, said epoxy resin composition comprising an epoxy resin represented by the general formula (1):



wherein each of R<sub>1</sub> to R<sub>5</sub> is a hydrogen atom and m is 0 or a positive number of 5 or less and a curing agent, wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight.